

CMLDM7005**SURFACE MOUNT SILICON
DUAL N-CHANNEL
ENHANCEMENT-MODE
MOSFET****SOT-563 CASE**www.centrasemi.com**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CMLDM7005 consists of dual N-Channel enhancement-mode silicon MOSFETs designed for high speed pulsed amplifier and driver applications. These MOSFETs offer very low $r_{DS(ON)}$ and low threshold voltage.

MARKING CODE: CC7**FEATURES:**

- ESD protection up to 2kV (Human Body Model)
- 350mW power dissipation
- Very low $r_{DS(ON)}$
- Low threshold voltage
- Logic level compatible
- Small, SOT-563 surface mount package
- Complementary dual P-Channel device: CMLDM8005

APPLICATIONS:

- Load switch/Level shifting
- Battery charging
- Boost switch
- Electro-luminescent backlighting

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Drain-Source Voltage	
Gate-Source Voltage	
Continuous Drain Current (Steady State - Note 1)	
Continuous Source Current (Body Diode)	
Maximum Pulsed Drain Current	
Power Dissipation (Note 1)	
Power Dissipation (Note 2)	
Power Dissipation (Note 2)	
Operating and Storage Junction Temperature	
Thermal Resistance (Note 1)	

SYMBOL		UNITS
V_{DS}	20	V
V_{GS}	8.0	V
I_D	650	mA
I_S	280	mA
I_{DM}	1.3	A
P_D	350	mW
P_D	300	mW
P_D	150	mW
T_J, T_{stg}	-65 to +150	$^\circ\text{C}$
θ_{JA}	357	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS PER TRANSISTOR: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{GSSF}, I_{GSSR}	$V_{GS}=4.5\text{V}, V_{DS}=0$			1.0	μA
I_{DSS}	$V_{DS}=16\text{V}, V_{GS}=0$			100	nA
BV_{DSS}	$V_{GS}=0, I_D=250\mu\text{A}$	20			V
$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5		1.1	V
V_{SD}	$V_{GS}=0, I_S=200\text{mA}$			1.1	V
$r_{DS(ON)}$	$V_{GS}=4.5\text{V}, I_D=600\text{mA}$		0.14	0.23	Ω
$r_{DS(ON)}$	$V_{GS}=2.5\text{V}, I_D=500\text{mA}$		0.2	0.275	Ω
$r_{DS(ON)}$	$V_{GS}=1.8\text{V}, I_D=350\text{mA}$			0.7	Ω
g_{FS}	$V_{DS}=10\text{V}, I_D=400\text{mA}$	1.0			S

Notes: (1) Ceramic or aluminum core PC Board with copper mounting pad area of 4.0mm^2

(2) FR-4 Epoxy PC Board with copper mounting pad area of 4.0mm^2

(3) FR-4 Epoxy PC Board with copper mounting pad area of 1.4mm^2

R5 (8-June 2015)

CMLDM7005

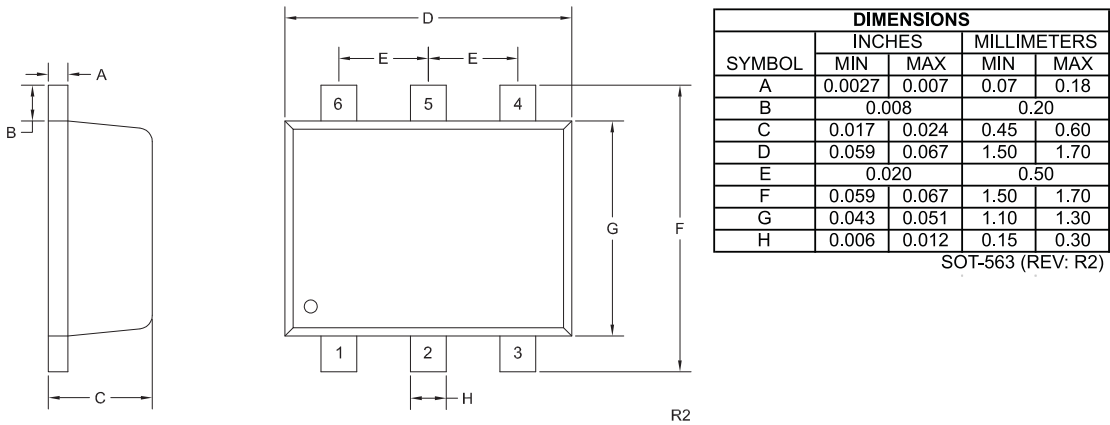
**SURFACE MOUNT SILICON
DUAL N-CHANNEL
ENHANCEMENT-MODE
MOSFET**



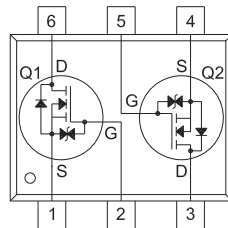
ELECTRICAL CHARACTERISTICS PER TRANSISTOR - Continued: ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	TYP	UNITS
C_{rss}	$V_{DS}=16\text{V}$, $V_{GS}=0$, $f=1.0\text{MHz}$	18	pF
C_{iss}	$V_{DS}=16\text{V}$, $V_{GS}=0$, $f=1.0\text{MHz}$	100	pF
C_{oss}	$V_{DS}=16\text{V}$, $V_{GS}=0$, $f=1.0\text{MHz}$	16	pF
$Q_{g(\text{tot})}$	$V_{DS}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=500\text{mA}$	1.58	nC
Q_{gs}	$V_{DS}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=500\text{mA}$	0.17	nC
Q_{gd}	$V_{DS}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=500\text{mA}$	0.24	nC
t_{on}	$V_{DD}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=200\text{mA}$, $R_G=10\Omega$	10	ns
t_{off}	$V_{DD}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=200\text{mA}$, $R_G=10\Omega$	25	ns

SOT-563 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



LEAD CODE:

- 1) Source Q1
- 2) Gate Q1
- 3) Drain Q2
- 4) Source Q2
- 5) Gate Q2
- 6) Drain Q1

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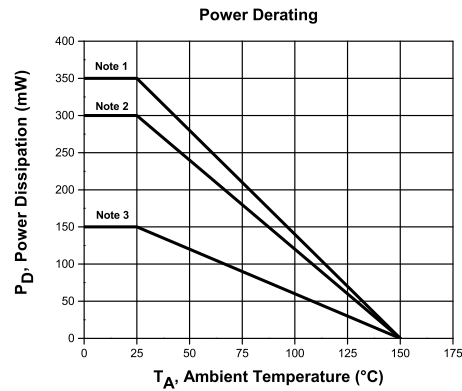
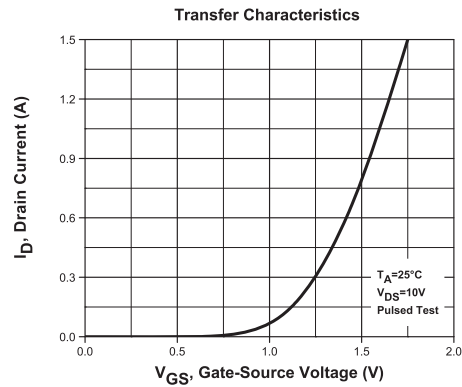
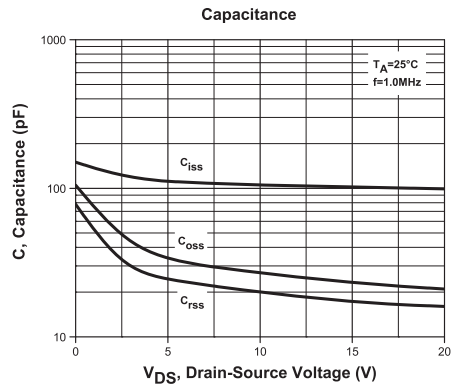
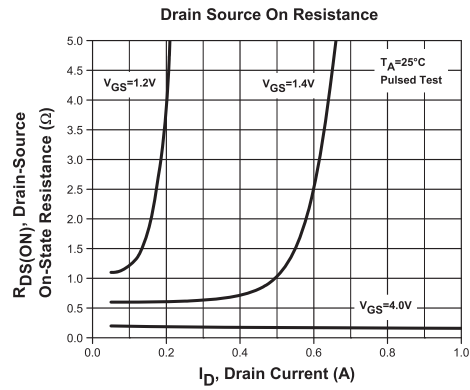
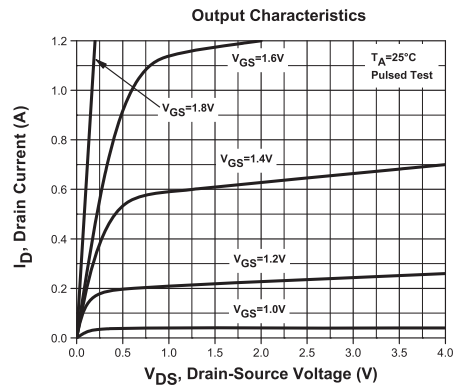
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N-CHANNEL TYPICAL ELECTRICAL CHARACTERISTICS



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OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centrasemi.com

Worldwide Field Representatives:
www.centrasemi.com/wwreps

Worldwide Distributors:
www.centrasemi.com/wwdistributors

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